

## Anam 3G/2G Cellular SMD Antenna

PA-25 PA-25

Part No: PA.25A

#### Description

Anam 3G/2G Cellular SMD Antenna 800 MHz to 2200 MHz

#### Features:

Compact High Efficiency Antenna Covers bands between 800 to 2200MHz Surface Mount Device Dimensions: 35\*5\*6mm Manufactured in an IATF16949 Approved Facility RoHS & REACH Compliant

#### www.taoglas.com



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# Introduction

1.





The PA.25A is ceramic 3G/2G cellular antenna designed for in-device mounting. The PA.25A is mounted through SMD process and can be used in varying applications based on it's small form factor of just 35\*6\*5mm.

Typical Applications Include:

- Body Worn Devices
- Hand-held IoT Devices
- Medical Devices
- Remote Monitoring

This ceramic multiband cellular antenna uses high grade ceramics which have been developed in Taoglas through years of expertise in delivering the right materials for high performance antennas. Taoglas, through constant research and development have designed a small form factor high efficiency antenna for use across cellular bands from 800MHz to 2170MHz.

The PA.25A is manufactured and tested in our IATF16949 approved facility.

The PA.25 is a unique SMD solution which is delivered on tape and reel. For very detailed integration information additional to this specification please download our comprehensive PA.25 integration application note from our website. For further information, please contact your regional Taoglas customer support team.



# Specification

2.

LTE Electrical								
Band	Frequency (MHz)	Efficiency (%)	Average Gain (dB)	Peak Gain (dBi)	Impedance	Polarization	Radiation Pattern	Max. input power
824-960	824-960	80.7	-0.93	2.91	50 Ω	Linear	Omni	2W
1710-2200	1710-2200	61.0	-2.14	4.56	50 12	Linear	UIIII	2 VV

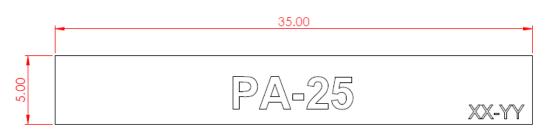
Mechanical				
Dimensions (mm) 35mm X 5mm X 6mm				
Material	Ceramic			
Termination	Ag (environmental-friendly Pb free)			
Weight	Зg			
EVB Connector	SMA-Female			

Environmental				
Operation Temperature	-40°C to 85°C			
Storage Temperature	-40°C to 105°C			
Moisture Sensitivity	Level 3			
RoHs and REACH Compliant	Yes			
MSL	Level 3 (168 Hours)			

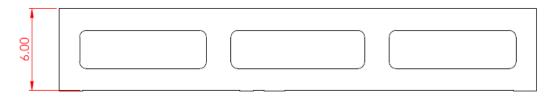
\* The antenna was tested on a 110\*40mm ground plane and covered.



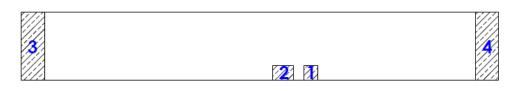
3.



TOP VIEW



FRONT VIEW



BOTTOM VIEW

Pin	Description
1	RF Feed
2	Ground
3, 4	Mechanical, Not Connected





# Antenna Integration Guide

The following is an example on how to integrate the PA.25A into a design. This antenna has 4 pins, where one pin is used for the RF Feed. Taoglas recommends using a minimum of 97x40mm ground plane (PCB) to ensure optimal performance.

The antenna should be placed mid-point on the short side of the PCB to take advantage of the ground plane.



Top view of PCB.

Please find the Integration files in Altium, 2D formats and the 3D model for the PA.25A here: <u>https://www.taoglas.com/product/anam-pa-25a-2g3g-smd-pifa-antenna-2/</u>

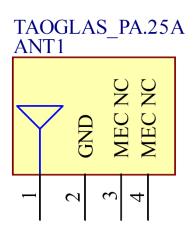


## 4.1 Schematic and Symbol Definition



Above is the 3D model of the PA.25A on the PCB.

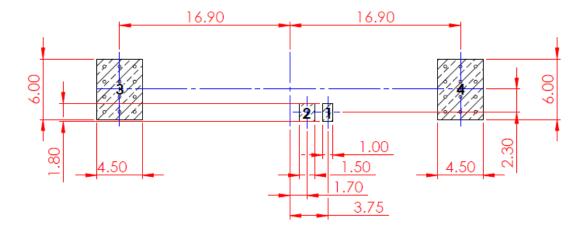
The circuit symbol for the PA.25A is shown below. The antenna has 4 pins as indicated below.



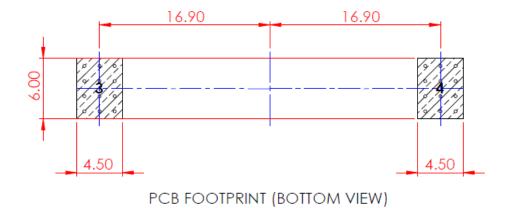
Pin	Description		
1	RF Feed		
2	Ground		
3, 4	Mechanical, Not Connected		



4.2 Antenna Footprint

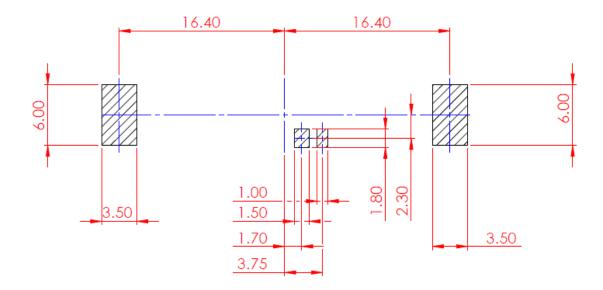


PCB FOOTPRINT (TOP VIEW)





## 4.3 Top Solder Paste

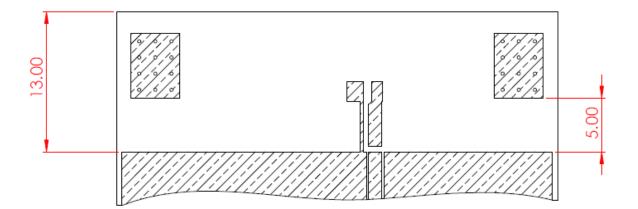


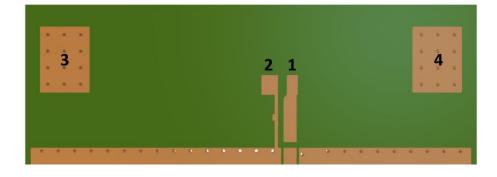


#### 4.4 Copper Clearance for PA.25A

The footprint and clearance on the PCB must comply with the antenna's specification. The PCB layout shown in the diagrams below demonstrates the PA.25A clearance area. The copper keep out area applies to all layers on the PCB.

The copper clearance area extends to 13mm in length around the antenna. The clearance between the mechanical pads and the ground plane should be 5mm.

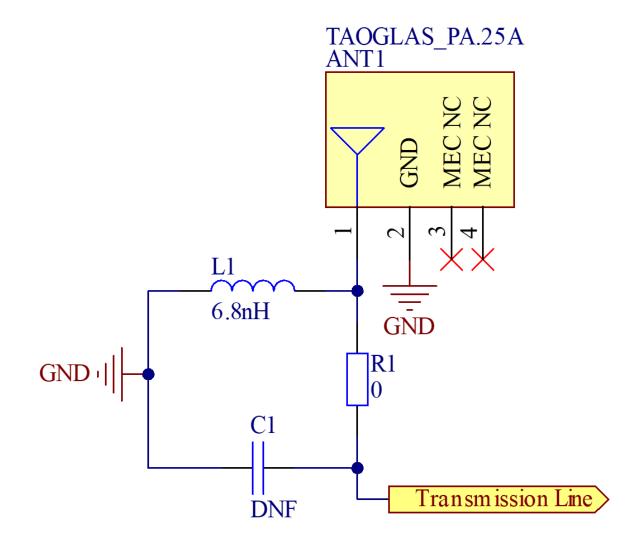






#### 4.5 Schematic Layout

Matching components with the PA.25A are required for the antenna to have optimal performance in the spaces specified in the schematic below. Additional matching components may be necessary for your device, Taoglas recommends incorporating extra component footprints, forming a "pi" network, for the PA.25A.

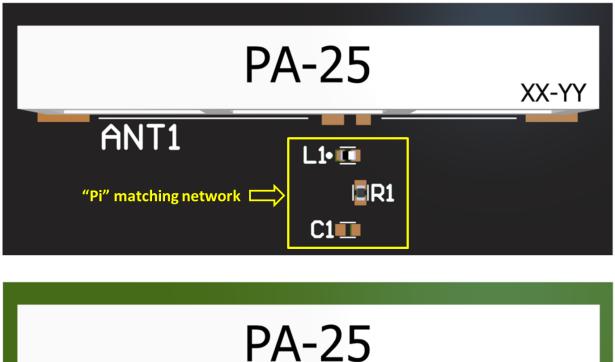


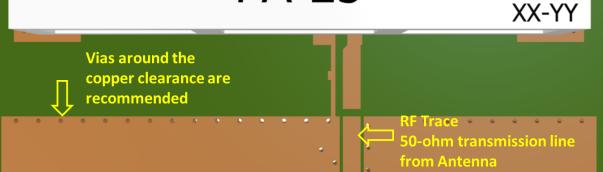
Designator	Туре	Value	Manufacturer	Manufacturer Part Number
C1	Capacitor	Not Fitted	-	-
L1	Inductor	6.8nH	TDK	MHQ1005P6N8JT000
R1	Resistor	0 Ohm	Panasonic	ERJ-2GE0R00X



#### 4.6 Antenna Integration

The PA.25A should be placed mid-point on the short side of the PCB to take advantage of the ground plane. The RF trace must maintain a 50 Ohm transmission line. A "Pi" Matching Network is recommended for the RF transmission line, the values and components for the matching circuit will depend on the tuning needed. Ground vias should be placed around the transmission line and the copper clearance area.





PA.25A antenna mounted on a PCB, showing transmission line and integration notes.



## 4.7 Final Integration

The top side image shown below highlights the antenna transmission line. Taoglas recommends using a minimum of 97x40mm ground plane (PCB) to ensure optimal performance.

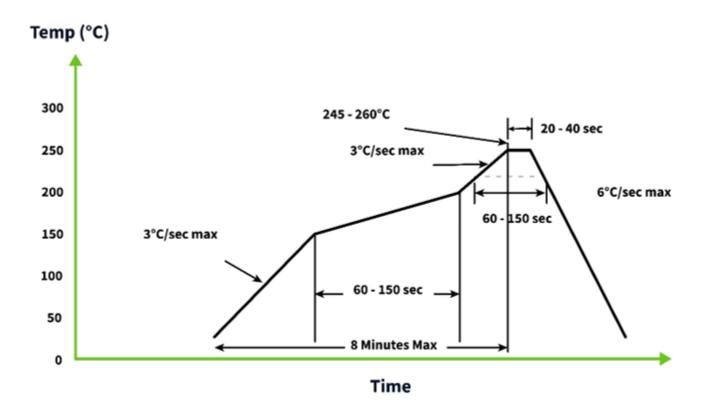








The PA.25A can be assembled by following the recommended soldering temperatures are as follows:



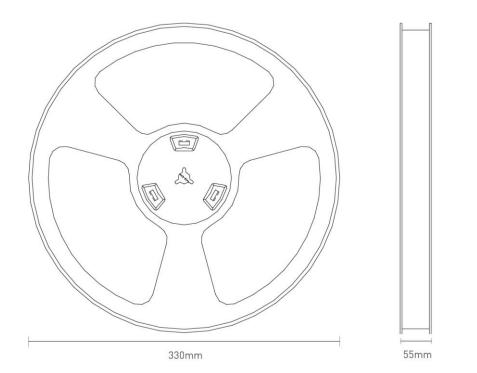
\*Temperatures listed within a tolerance of +/- 10º C

Smaller components are typically mounted on the first pass, however, we do advise mounting the PA.25A when placing larger components on the board during subsequent reflows.

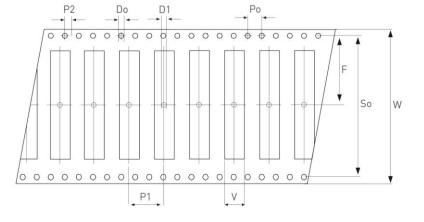
Note: Soldering flux classified ROLO under IPC J-STD-004 is recommended.



450 pc PA.25.A 1 reel per small inner box Dimensions - 330\*55mm Weight - 2000g

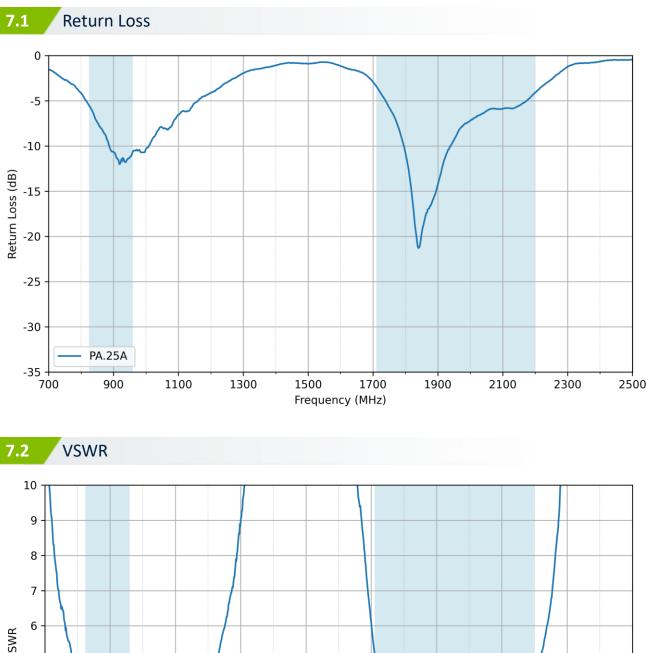


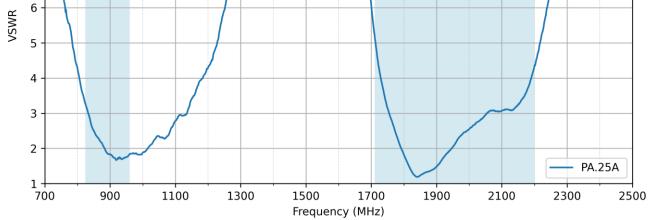
Symbol	Spec
Po	$4.0 \pm 0.10$
P1	$12.0 \pm 0.10$
P2	$2.0 \pm 0.15$
Do	1.5
D1	0.7
F	$26.2 \pm 0.10$
So	$52.4 \pm 0.10$
W	56.0 ± 0.30
V	$5.5 \pm 0.10$





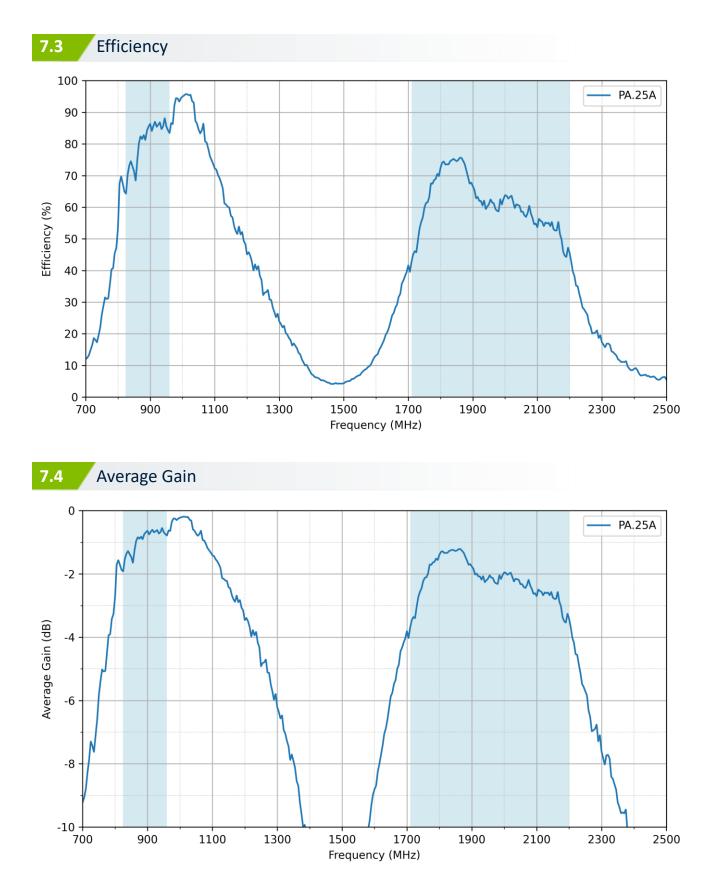




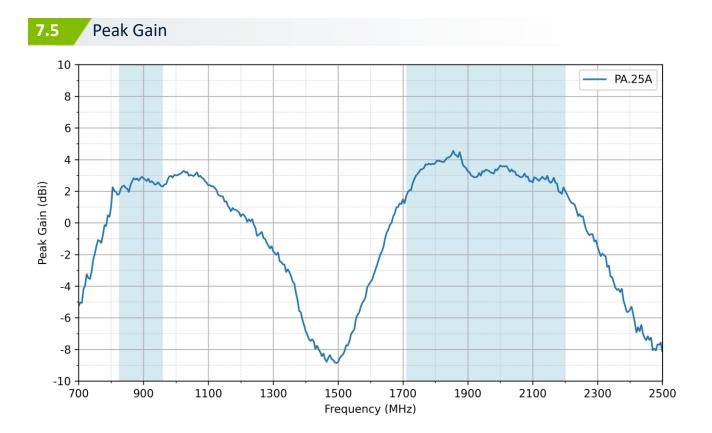


7.







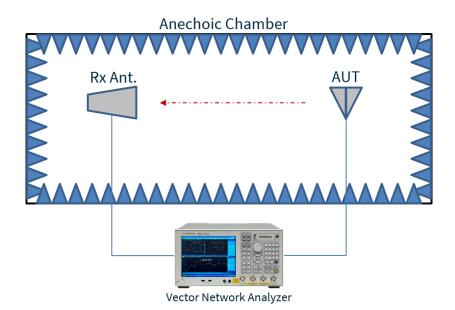








8.

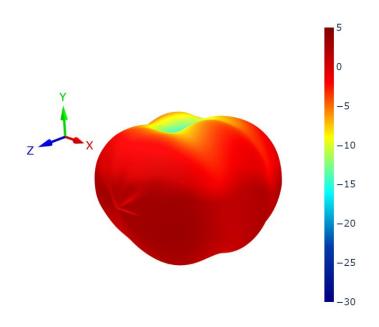


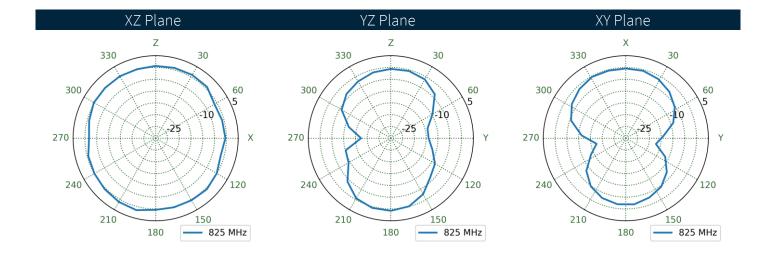


Chamber Test Set-up



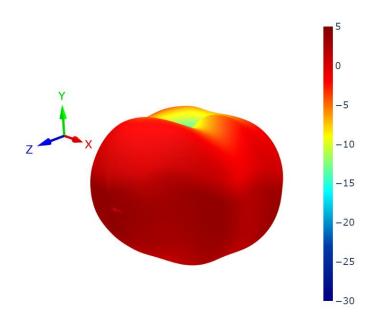
#### 8.2 Patterns at 824 MHz

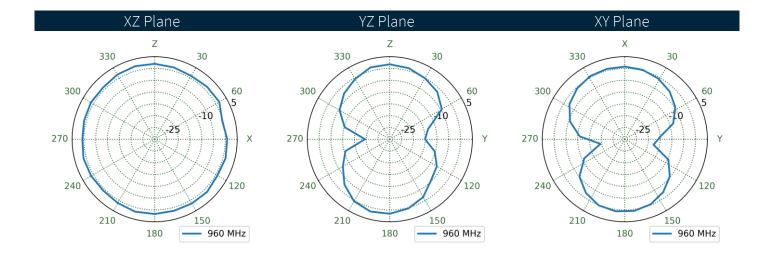






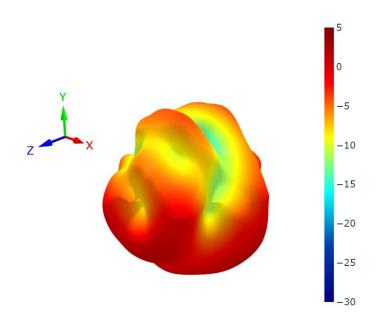
#### 8.3 Patterns at 960 MHz

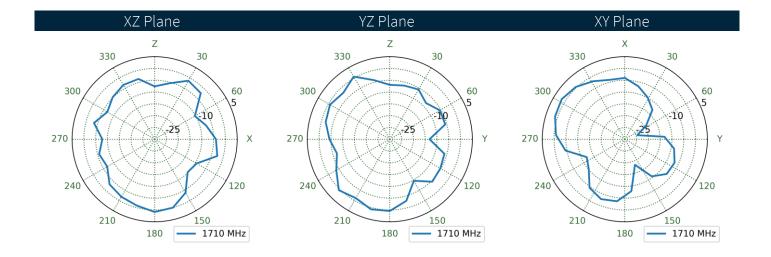






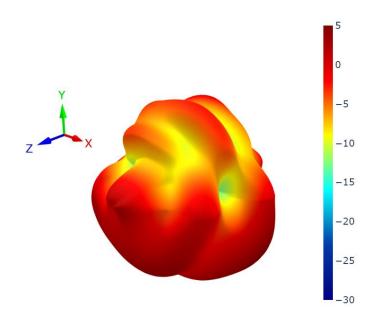
## 8.4 Patterns at 1710 MHz

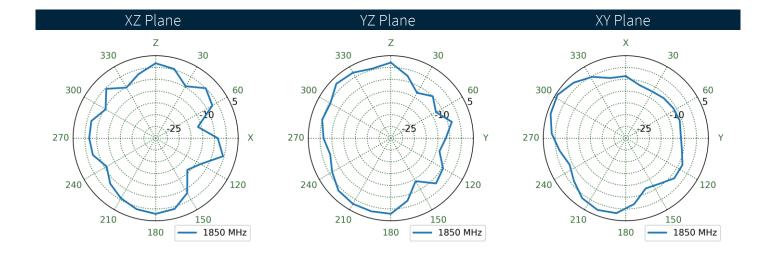






#### 8.5 Patterns at 1850 MHz







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SPE-11-8-061 – PA.25A				
Revision: N (Current Version)				
Date: 2024-04-08				
Changes: Updated Antenna Integration Guide and Datasheet Flow				
Changes Made by: Cesar Sousa				

#### **Previous Revisions**

Revision: M				
Date:	2023-10-25			
Changes:	Updated Solder Reflow Profile			
Changes Made by:	Cesar Sousa			

Revision: H	
Date:	2016-01-18
Changes:	
Changes Made by:	Technical Writer

Revision: L	
Date:	2022-02-23
Changes:	Added integration guide
Changes Made by:	Gary West

Revision: K	
Date:	2020-11-10
Changes:	Specifications table amended - Moisture Sensitivity Level 3
Changes Made by:	Dan Cantwell

s Made by:	Dan Cantwell	Changes Made by:	Tec
: J		Revision: E	
Date:	2016-12-21	Date:	201
Changes:		Changes:	

Changes:	
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Changes Made by:	Technical Writer
с ,	
Povision: F	

Revision: E	
Date:	2012-12-06
Changes:	
Changes Made by:	Technical Writer

Revision: G

**Revision: F** 

Date:

Changes:

Changes Made by:

2013-09-03

Aine Doyle

Date: 2013-03-21

Amended Dimensions

Revision: I	
Date:	2016-09-22
Changes:	Updated PAD, EBV drawing and image
Changes Made by:	Andy Mahoney

Technical Writer

Revision: D	
Date:	2011-09-07
Changes:	
Changes Made by:	Technical Writer

Revision: J

Changes Made by:



Revision: C	
Date:	
Changes:	
Changes Made by:	Technical Writer
Revision: B	
Date:	
Changes:	
Changes Made by:	Technical Writer
Revision: A (Origina	al First Release)
Date:	2010-08-18
Notes:	
Author:	Technical Writer